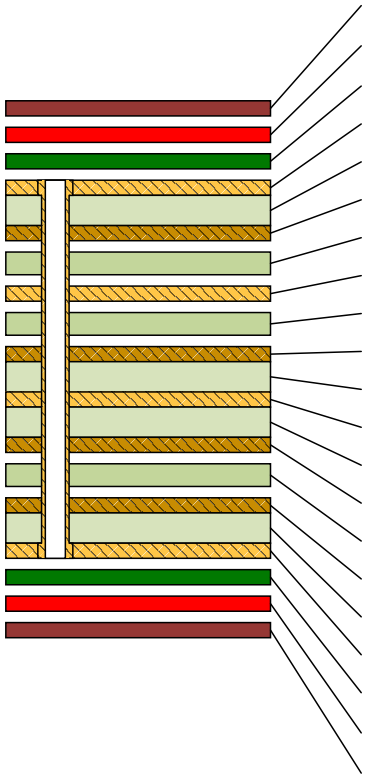
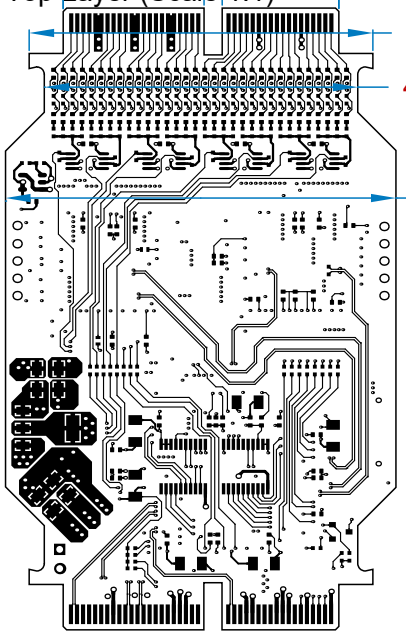
Layer Stack Legend



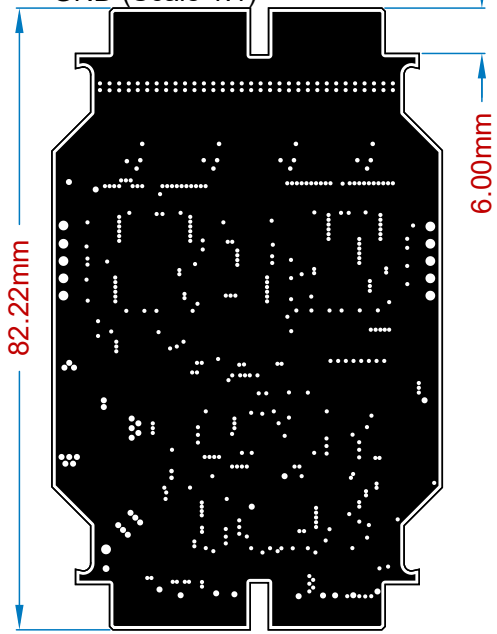
Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Paste			Paste Mask	GTP
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.01mm	Solder Resist	Solder Mask	GTS
Copper	Top Layer	0.04mm		Signal	GTL
Core		*0.25mm*	*FR-4*	*Dielectric*	
Copper	GND	0.04mm		Internal Plane	GP1
Prepreg		*0.13mm*	*FR-4*	*Dielectric*	
Copper	AUX Route Horz	0.04mm		Signal	G1
Prepreg		*0.13mm*	*FR-4*	*Dielectric*	
Copper	2.5VF	0.04mm		Internal Plane	GP2
Core		*0.25mm*		*Dielectric*	
Copper	AUX Route Vert	0.04mm		Signal	G2
Core		*0.25mm*	*FR-4*	*Dielectric*	
Copper	1.2V	0.04mm		Internal Plane	GP3
Prepreg		*0.13mm*		*Dielectric*	
Copper	2.5V	0.04mm		Internal Plane	GP4
Core		*0.25mm*	*FR-4*	*Dielectric*	
Copper	Bottom Layer	0.04mm		Signal	GBL
Surface Material	Bottom Solder	0.01mm	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
	Bottom Paste			Paste Mask	GBP

Total thickness: 1.70mm

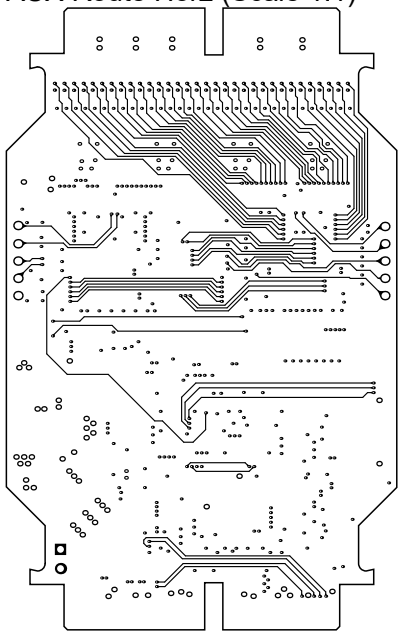
Top Layer (Scale 1:1)



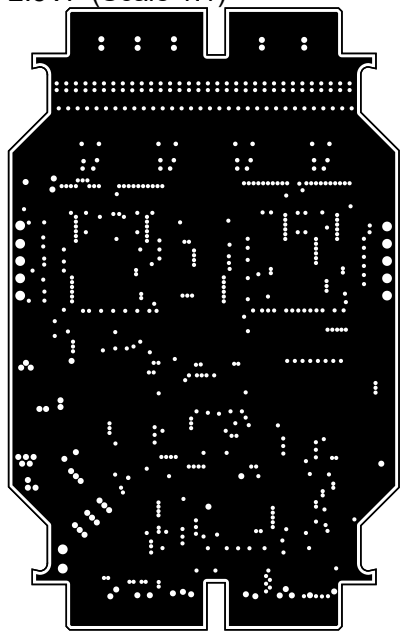
GND (Scale 1:1)



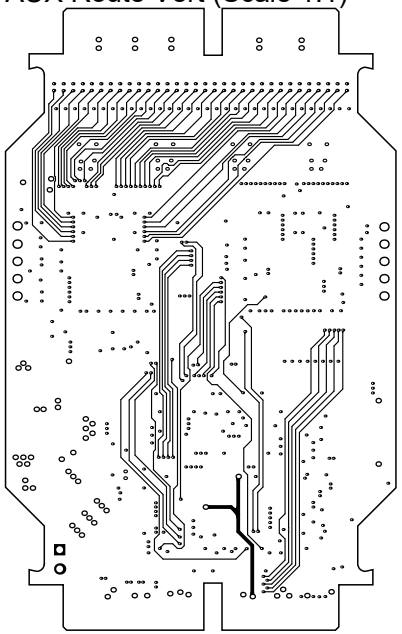
AUX Route Horz (Scale 1:1)



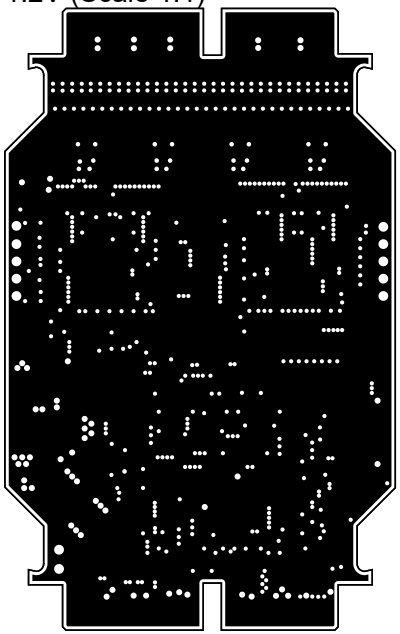
2.5VF (Scale 1:1)



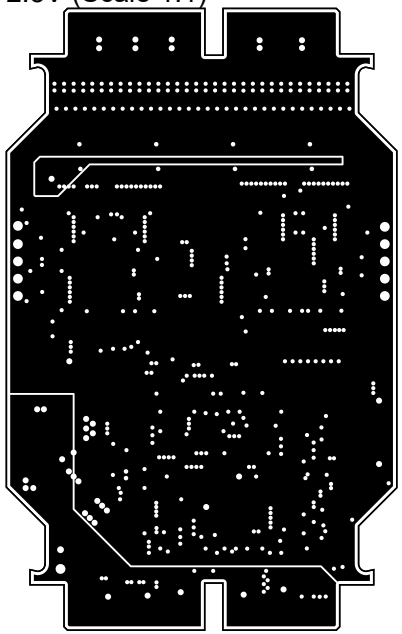
AUX Route Vert (Scale 1:1)



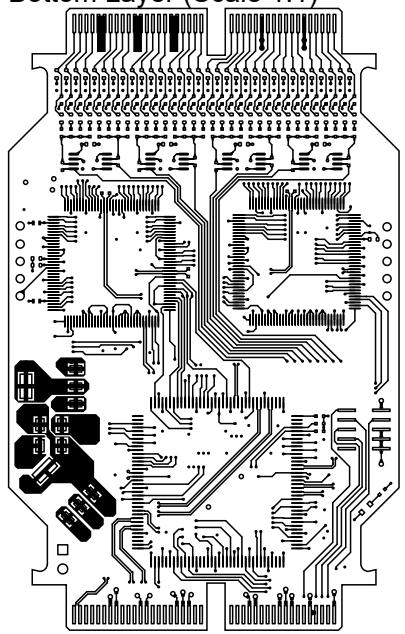
1.2V (Scale 1:1)



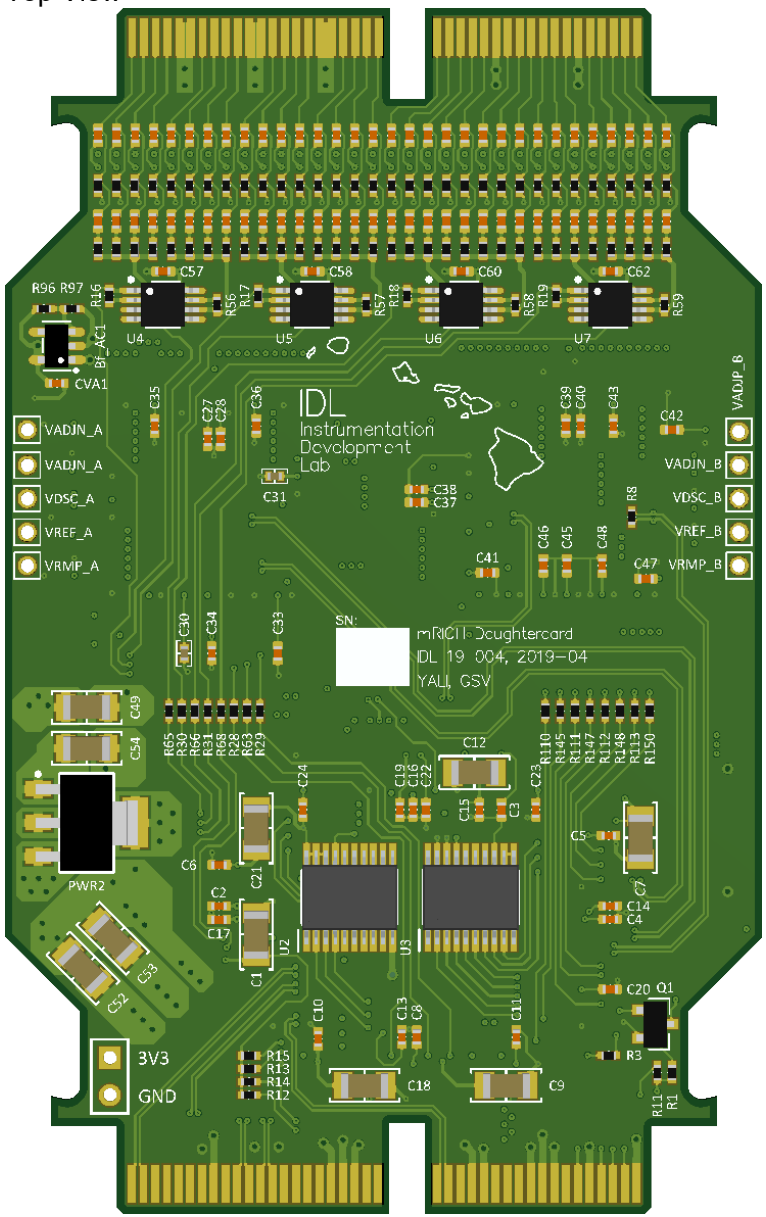
2.5V (Scale 1:1)



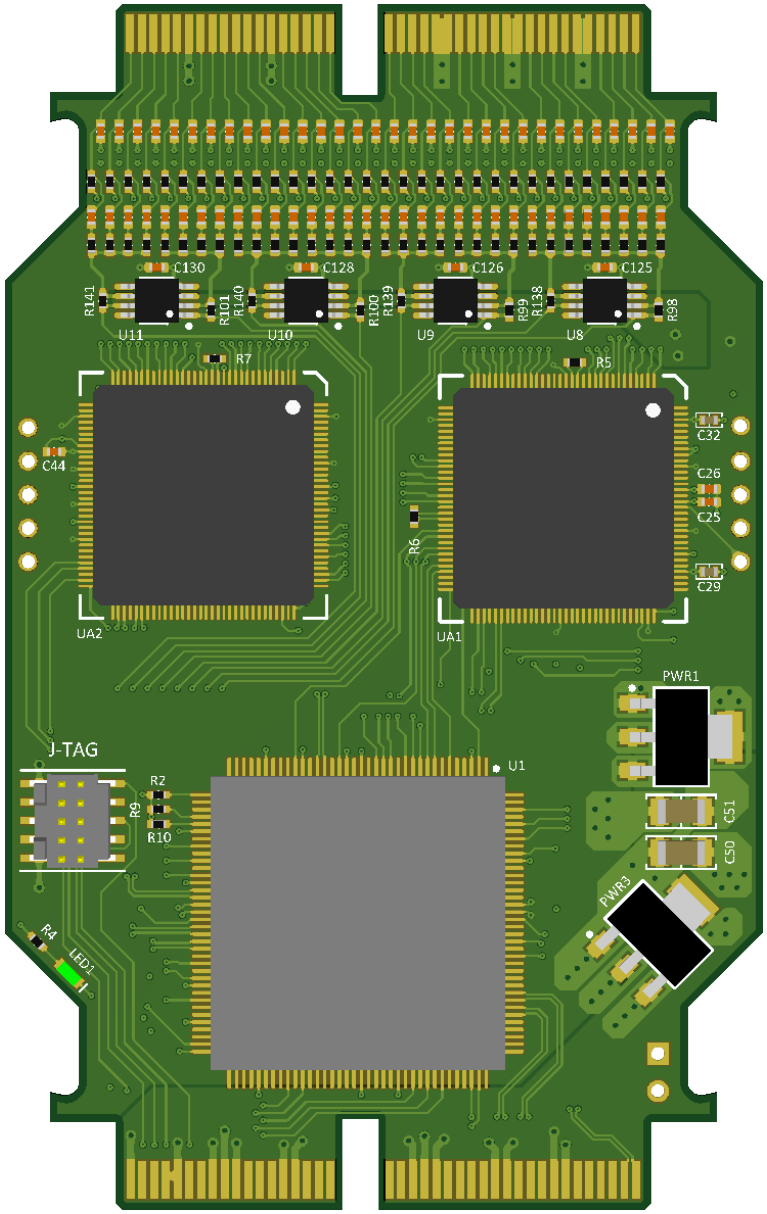
Bottom Layer (Scale 1:1)



Top View



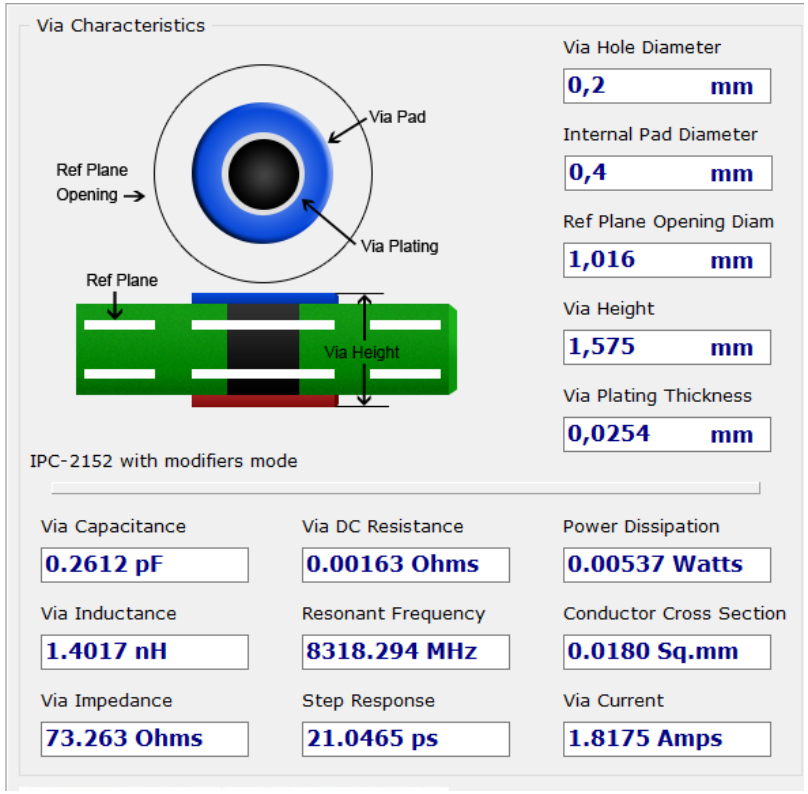
Bottom View

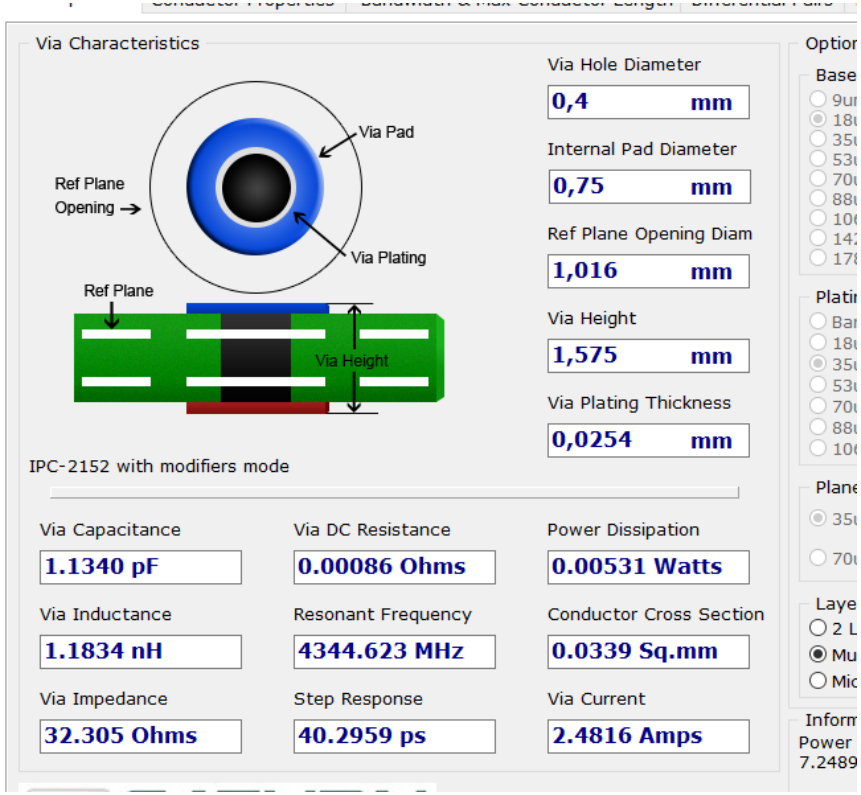


Drill Table

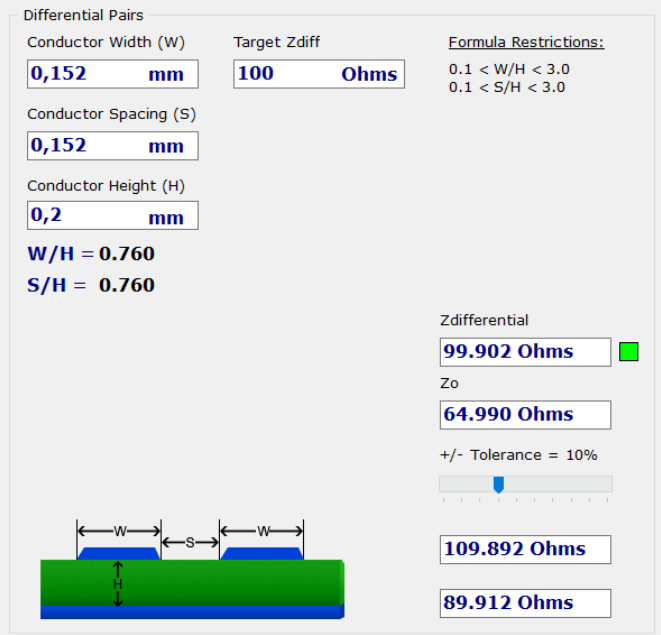
Symbol	Count	Hole Size	Plated	Hole Tolerance
◇	484	0.15mm	Plated	None
⊠	26	0.20mm	Plated	None
✣	66	0.40mm	Plated	None
○	10	0.89mm	Plated	None
□	2	0.90mm	Plated	None
	588 Total			

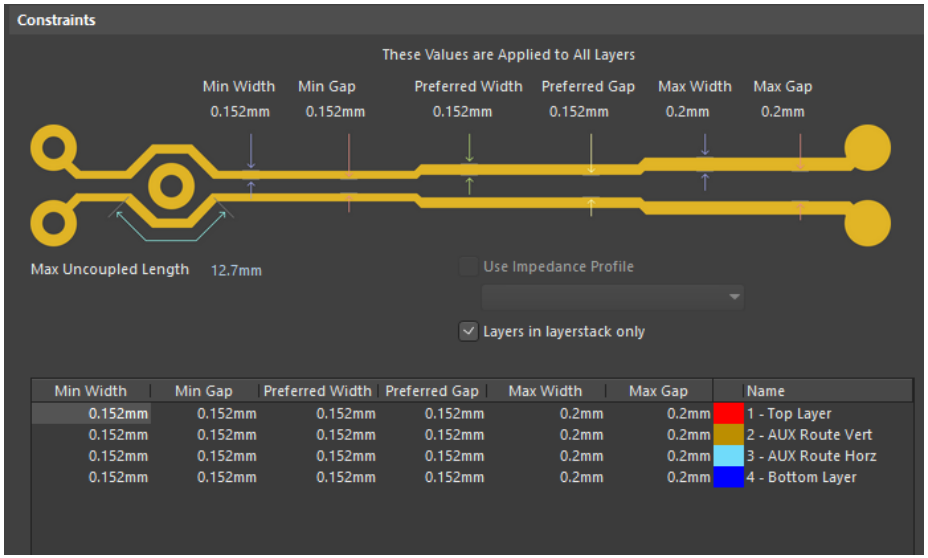
The current for the vias calculated as follows





The diff pair impedance was calculated as follows





The current for the minimum trace width was calculated as follows